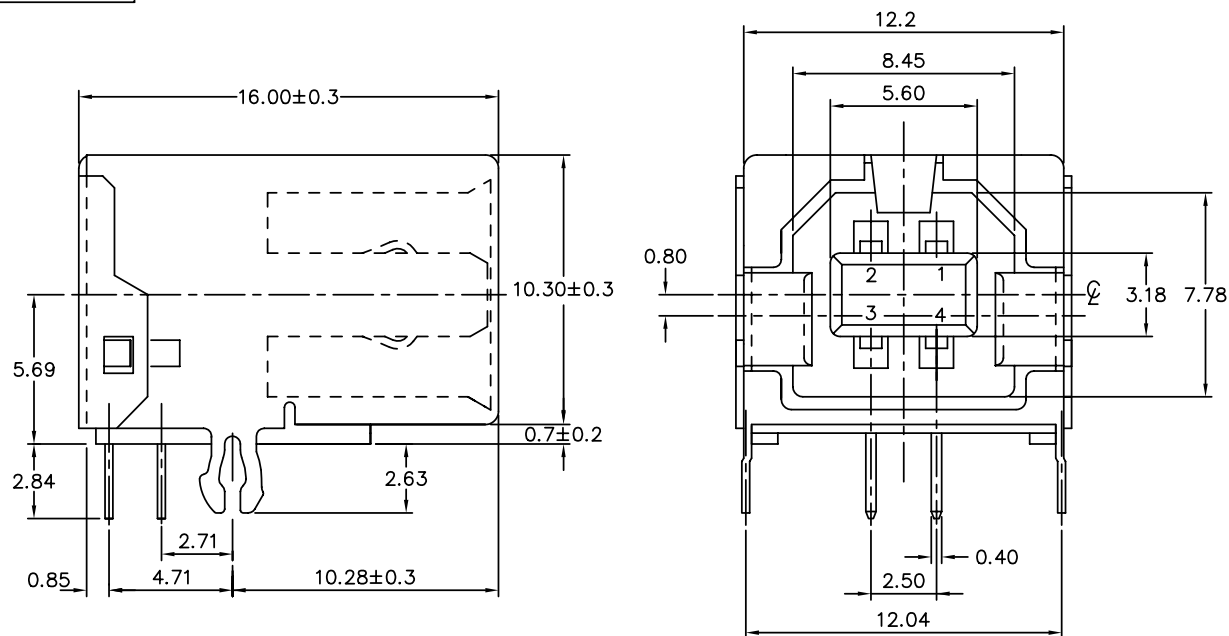
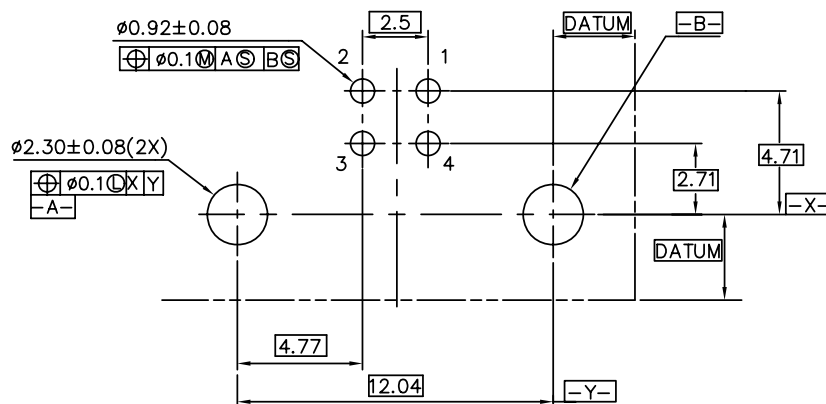


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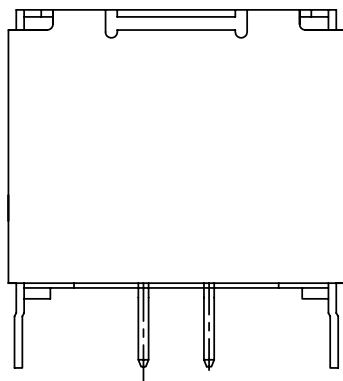
61729 - X X X X X P S LF

LEAD FREE OPTION

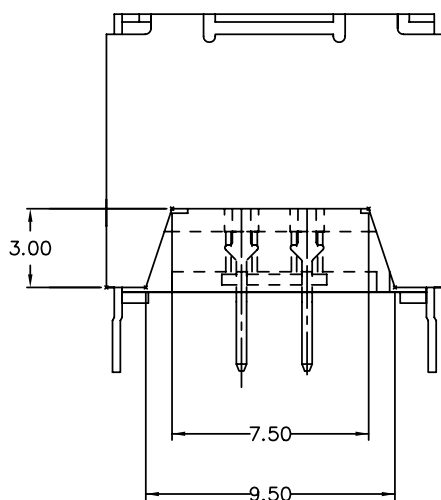


P.C. BOARD LAYOUT

[illegible]



TYPE "1" FULL BACK



TYPE "2" PARTIAL BACK

NOTES:

1. MATERIAL:
SHIELD & CONTACTS: COPPER ALLOY
HOUSING: UL 94V-0 ,HIGHT TEMPERATURE THERMOPLASTIC.
COLOR: SEE PRODUCT NUMBER CODE.
2. PLATING: SEE PRODUCT NUMBER CODE.
SHIELD: BRIGHT TIN
NICKEL UNDERPLATE.
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)
5. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.
8. THE PART CAN BE USED FOR PIP PROCESS.

mat'l. code		surface	tolerance	projection	product family
		ISO 1301 ✓	ISO 406 ISO 1101		USB2.0
ltn	ecn	nodr	date	title	
-	-	-	-	USB RECEPTACLE B TYPE	
		angle	0.0±0.3	mm	
		0°±2'	0.00±0.20	scale 4:1	
		0.000±0.10			
dr	LQ.LEI	2013-12-10		dwg no	sheet 2 of 2 size
enr	LQ.LEI	2013-12-10		61729	A4
chr	RICK BIAN	2013-12-10		type	Product Customer Drawing
appd	RICK BIAN	2013-12-17			
sheet	revision-				
index	sheet -				